

WLCSP6_A0005Hi

wafer level chip-size package; 6 bumps

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP6
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	11-1-2012

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.74	-	0.77	0.8	mm
E	package width	1.14	-	1.17	1.2	mm
A	seated height	0.475	-	0.515	0.555	mm
A ₂	package height	0.29	-	0.315	0.34	mm
n ₂	actual quantity of termination	-	-	6	-	

2. Package outline

Fig. 1. Package outline WLCSP6 (WLCSP6_A0005Hi)



3. Legal information

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